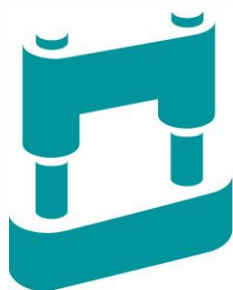
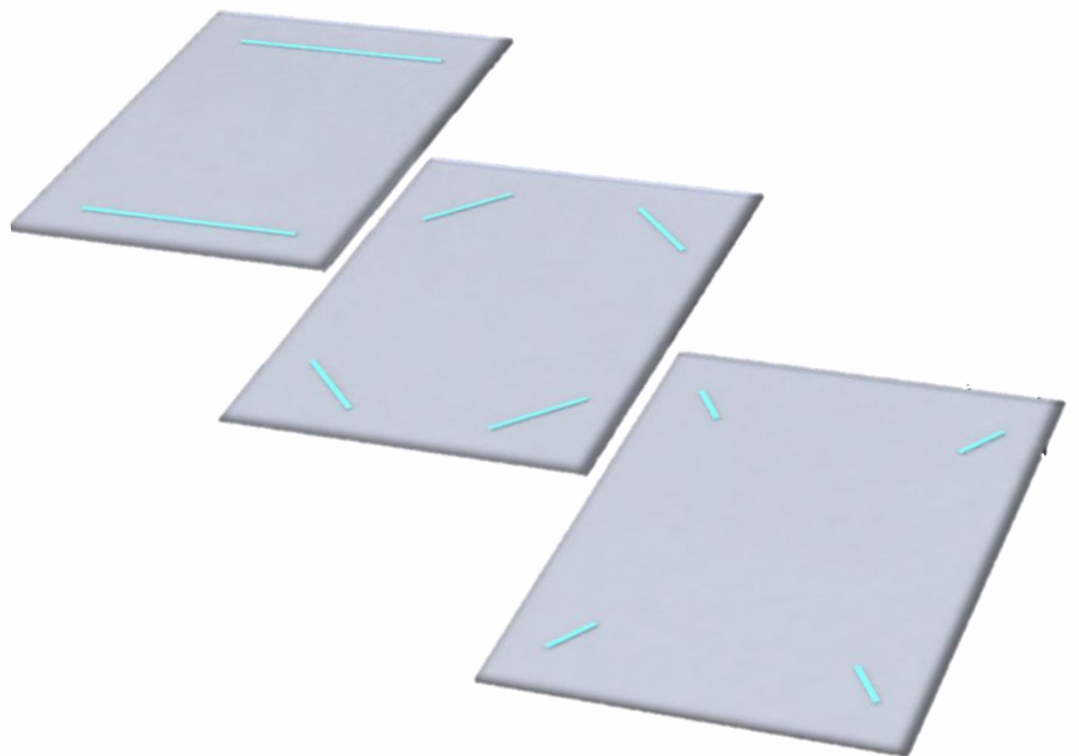


Introducing TFPS - Preforms

# TFPS

**Tilt Free Preform Solder**

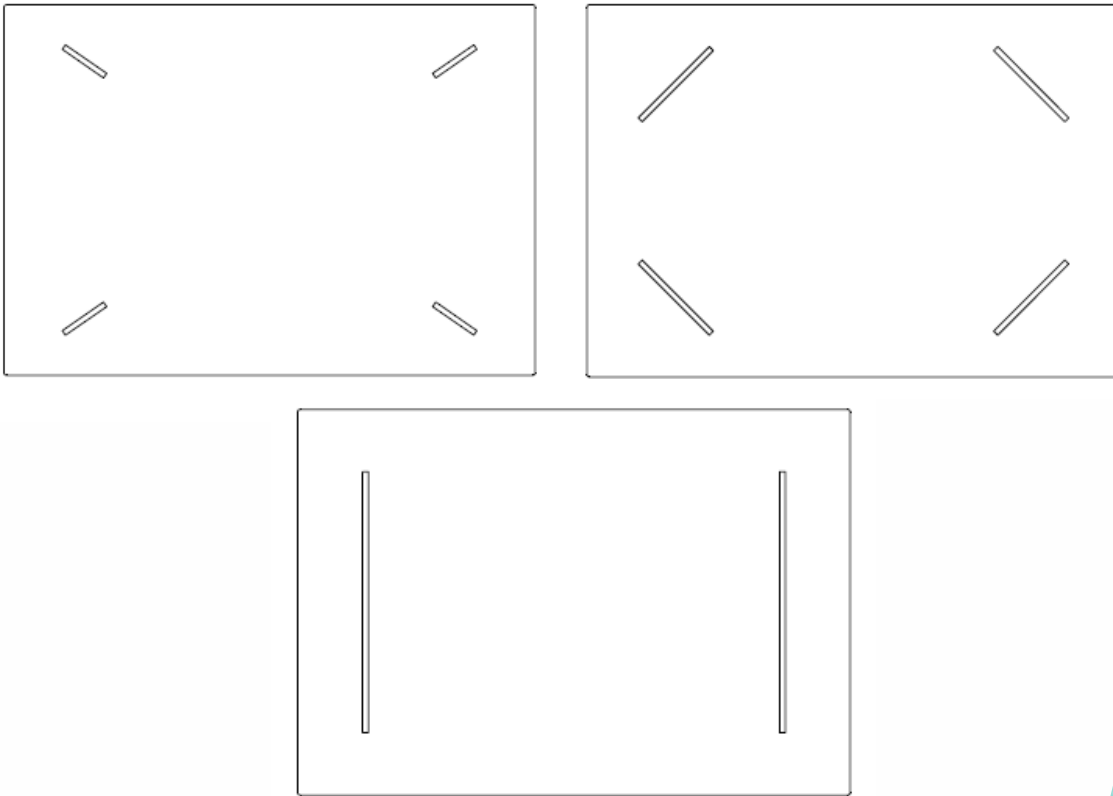


# PFARR

WIR BRINGEN LÖT IN FORM  
*GETTING SOLDER INTO SHAPE*

# Concept

Wires of high melting alloy are integrated into the preform, with the length, direction, and number tailored to customer requirements. This design provides effective support to the components during soldering, preventing tilting of the component by its own weight.



## Features

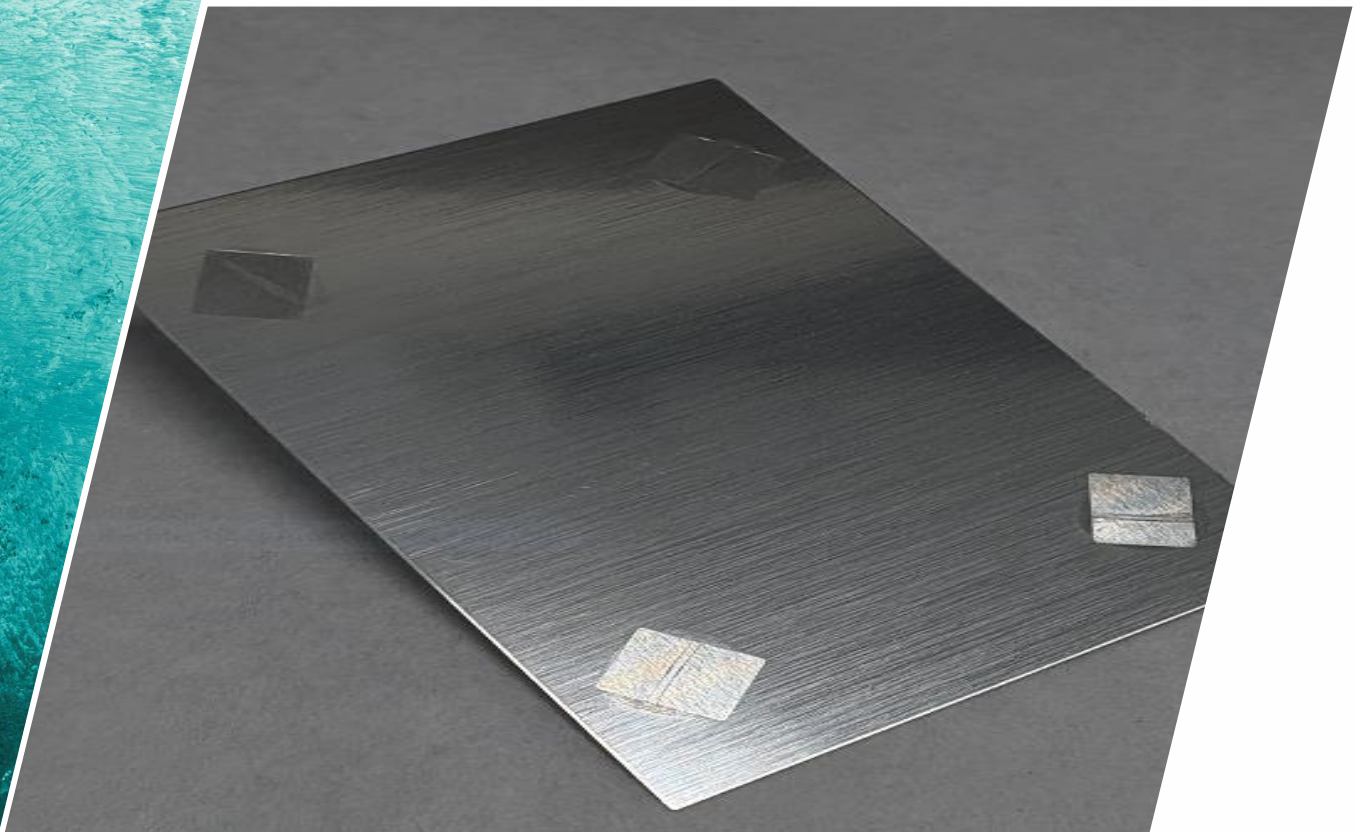
- **Controlled Bond Line Thickness:** Integrated wires of high melting point alloys such as Copper or Nickel ensure precise bond line control as they do not melt during the soldering process
- **Wire Height:** The height of integrated wires can range up to a little less than the preform height, providing adequate support and maintain BLT
- **System Soldering Compatibility:** Ideal for system soldering with preform thickness ranging from 150µm to 600µm
- **Customizable Design:** Layout, direction, length, and number of wires can be tailored to meet specific customer requirements





# Benefits

- **Reduction of Tilt:** Minimizes tilt during soldering
- **Design Stabilization:** Complex designs for solder joints can be stabilized by intelligently positioning and directing the wires
- **Enhanced Thermal Conductivity:** Provides improved thermal conductivity for better performance
- **Efficient Support:** Achieves support with minimal wire material, thereby maintaining the composition of the parent alloy
- **Excellent Wetting Characteristics:** Exhibits wetting characteristics similar to corresponding monolithic solder preforms



**For further information contact us:**



[www.pfarr.de](http://www.pfarr.de)

